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disclosures of which, except to any extent that they may be inconsistent with any explicit statement herein or with other more recently developed knowledge in the art, are hereby incorporated herein by reference: U. S. National Application Serial Nos. 08/344,829; 08/464,609; 08/569,177, now abandoned; 08/638,268, now abandoned; 60/036,606, now abandoned; and 08/849,704, now abandoned; PCT Application Nos. US96/19144; and US96/02677; and Patents 5,900,073; 5,891,268; 5,776,265; 5,645,650; 5,683,816; 5,595,611; 5,498,300; 5,472,522; 5,451,271; 5,378,292; 5,261,973; 5,143,562; 5,125,989; 5,082,511; 5,073,196; 5,045,130; 5,000,799; 4.992.116; 4.961.794; 4.927.472; 4.880.467; 4.874.480; 4.849.031; 4.722.753; 4.717.431; 4,673,444; 4,643,778; 4,639,295; 4,637,838; 4,612,060; 4,596,607; 4,595,424; 4,565,585; 4.559.087; 4.539.051; 4.529,451; 4.517,029; 4.515,643; 4,486,241; 4,443,273; 4,419,199; 4,419,147; 4,416,705; 4,402,765; 4,385,096; 4,377,487; 4,338,141; 4,311,535; 4,292,096; 4,289,546; 4,265,677; 4,220,486; 4,142,917; 4,108,690; 4,063,968; 3,939,014; 3,932,287; 3,870,573; 3,860,455; 3,850,700; 3,839,099; 3,795,548; 3,758,349; 3,723,334; 3,723,192; 3,706,604; 3,697,332; 3,671,332; 3,645,797; 3,619,300; 3,615,912; 3,607,453; 3,573,997; 3,565,699; 3,547,711; 3,533,859; 3,525,651; 3,519,495; 3,519,494, 3,516,875; 3,515,600; 3,493,400; 3,484,304; Re 27,896; 3,467,589; 3,454,483; 3,450,579; 3,450,578; 3,450,577; 3,449,222; 3,444,007; 3,401,065; 3,397,093; 3,397,092; 3,380,859; 3,338,755; 3,297,493; 3,294,593; 3,268,367; 3,240,633; 3,218,200; 3,197,344; 3,161,549; 3,154,438; 3,146,133;3,133,005; 3,101,286; 3,046,165; 3,015,594; 3,007,817; 2,979,430; 2,891,884; 2,882,189; $2,875,111; \quad 2,840,498; \quad 2,835,618; \quad 2,835,617; \quad 2,832,707; \quad 2,819,193; \quad 2,813,814; \quad 2,813,813;$ 2,813,812; 2,798,829; 2,758,949; 2,744,555; 2,743,204; 2,724,668; 2,702,768; 2,665,231; 2,657,156; 2,609,308; 2,591,479, 2,564,864; 2,540,314; 2,298,312; 2,298,280; 2,245,609;

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2,132,883; 2,121,574; 2,121,520; 2,120,212; 2,114,151; 2,076,869; 1,660,661; 1,654,716;

1,651,694; 1,639,694; 1,610,362; 1,485,025; 1,388,325; 1,377,174; 1,341,100; 1,320,734;

1,317,351; 1,292,352; 1,290,476; 1,287,605; 1,254,264; 1,254,263; 1,248,053; 1,219,526;

1,215,463; and 1,206,075.

Please amend the paragraph beginning at line 15 on page 9 of the specification and ending at line 4 on page 10 of the specification as follows:

In addition to the above-considered ingredients of a conventional phosphating composition, a composition according to the invention must include at least one adhesion-promoting substance, which preferably is selected from the group consisting of (i) film-forming organic substances, (ii) polymers of vinyl phenols modified by substitution of substituted aminomethyl moieties on the aromatic rings of the polymers of vinyl phenols, as described in more detail in one or more of U. S. Patents 5,891,952, 5,298,289, 5,266,410, 5,068,299, and 5,063,089, the entire disclosures of all of which, except for any part that may be inconsistent with any explicit statement herein, are hereby incorporated herein by reference, this type of polymers being hereinafter denoted briefly as "aminophenolic polymers" (these materials may be, but need not necessarily be, film-forming organic substances also), and (iii) inorganic oxides of one of the elements silicon, aluminum, titanium, and zirconium. A film-forming organic substance is defined for this purpose as an organic material that has all of the following properties:

- when isolated from other materials, the film-forming organic substance is a solid at 30 °C
 and normal atmospheric pressure;
- the film-forming organic substance can be dissolved or stably dispersed in water to form a homogeneous solution in which the film-forming organic substance constitutes at least 5 % of the homogeneous solution; and
- when a homogeneous solution of the film-forming organic substance in water that contains at least 0.10 cubic centimeters volume of the isolated film-forming organic substance is dried at a temperature of 30 °C in a walled container with a base area of 1.0 square centimeter and walls perpendicular to the base, there is formed in the base of said container a

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continuous solid article of the film-forming organic substance, said continuous solid article, after being separated from the container in which it was formed by drying, having sufficient cohesion to sustain its integrity against the force of natural gravity of the Earth.